

General Description

The Sanrise SRT045N060H is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and synchronous rectification.

The SRT045N060H break down voltage is 45V and it has a high rugged avalanche characteristics. The SRT045N060H is available in PDFN5*6 and PDFN3.3*3.3 packages.

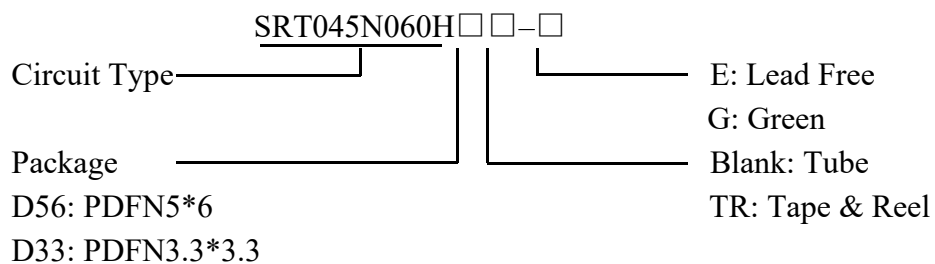
Features

- Ultra Low
 $R_{DS(ON_TYP)} = 5.1m\Omega, PDFN5*6 @ V_{GS} = 10V.$
 $R_{DS(ON_TYP)} = 5.6m\Omega, PDFN3.3*3.3 @ V_{GS} = 10V.$
- Ultra Low Gate Charge, $Q_g = 13nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved
- Non-automotive Qualified

Application

- High Power Supply
- E-Tools
- Motor Driver
- BMS

Ordering Information



Symbol

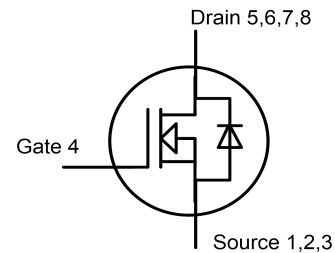


Figure 1 Symbol of SRT045N060H

Package Type

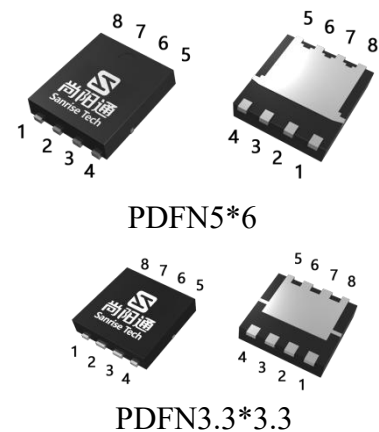


Figure 2 Package Type of SRT045N060H

PDFN5*6	SRT045N060HD56TR-G	SRT045N060HD56G	Tape & Reel
PDFN3.3*3.3	SRT045N060HD33TR-G	045N060HD33G	Tape & Reel

Absolute Maximum Ratings

Parameter		Symbol	Rating		Unit
Drain-Source Voltage		V_{DSS}	45		V
Gate-Source Voltage		V_{GSS}	±20		V
Continuous Drain Current, Silicon	$T_C=25^\circ\text{C}$	I_D	PDFN5*6	52	A
			PDFN3.3*3.3	48	
	$T_C=125^\circ\text{C}$		PDFN5*6	23	
			PDFN3.3*3.3	21.5	
Pulsed Drain Current (Note 2)		I_{DM}	160		A
Power Dissipation ($T_C = 25^\circ\text{C}$)		P_D	32.9		W
Avalanche Destructive Energy, Single Pulse (Note 4)		E_{AS_Limit}	56		mJ
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	9		mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.01		mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	6.0		A
Continuous Diode Forward Current		I_S	52		A
Diode Pulse Current		$I_{S.PULSE}$	160		A
Operating Junction Temperature		T_J	150		$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 to 150		$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260		$^\circ\text{C}$

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS}= 6.0\text{A}$, $V_{DD}= 20\text{V}$, $R_G= 25\Omega$, Starting $T_J= 25^\circ\text{C}$
- $I_{AS_Limit}= 15\text{A}$, $V_{DD} = 20\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	PDFN5*6	R_{thJC}			3.8	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient		R_{thJA}			50	
Thermal Resistance, Junction-to-Case	PDFN3.3*3.3	R_{thJC}			4.2	
Thermal Resistance, Junction-to-Ambient		R_{thJA}			56	

Electrical Characteristics

$T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Statistic Characteristics							
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	45			V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=45V, V_{GS}=0V$			1	μA	
Gate-Body Leakage Current	Forward	$V_{GS}=20V, V_{DS}=0V$			200	nA	
	Reverse	$V_{GS}=-20V, V_{DS}=0V$			-200		
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	2.0	3.0	4.0	V	
Static Drain-Source On-Resistance	PDFN5*6	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		5.1	6.0	$m\Omega$
	PDFN3.3*3.3	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		5.6	6.5	$m\Omega$
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		2.3		Ω	
Dynamic Characteristics							
Input Capacitance	C_{ISS}	$V_{DS}=20V, V_{GS}=0V, f=1MHz$		870		pF	
Output Capacitance	C_{OSS}			290		pF	
Reverse Transfer Capacitance	C_{RSS}			18		pF	
Effective output capacitance, energy related <small>NOTE5</small>	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 20V$		310		pF	
Effective output capacitance, time related <small>NOTE6</small>	$C_{O(tr)}$			430			
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20V, I_D=10A, R_G=1.6\Omega, V_{GS}=10V$		6		ns	
Rise Time	t_r			3			
Turn-off Delay Time	$t_{d(off)}$			25			
Fall Time	t_f			4			
Gate Charge Characteristics							
Gate to Source Charge	Q_{gs}	$V_{DD}=20V, I_D=10A, V_{GS}=0 \text{ to } 10V$		4.2		nC	
Gate to Drain Charge	Q_{gd}			2.1			
Gate Charge Total	Q_g			13			
Gate Plateau Voltage	$V_{plateau}$			5.0		V	
Gate Charge Total, sync FET	Q_g	$V_{DD}=0.1V, V_{GS}=0 \text{ to } 10V$		11.9		nC	
Reverse Diode Characteristics							
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=10A$		0.82	1.0	V	
Reverse Recovery Time	t_{rr}	$V_R=20V, I_F=10A, dI_F/dt=100A/\mu s$		18		ns	
Reverse Recovery Charge	Q_{rr}			12		nC	
Peak Reverse Recovery Current	I_{rrm}			1.3		A	

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 32V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 32V



Sanrise Technology Limited Company

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